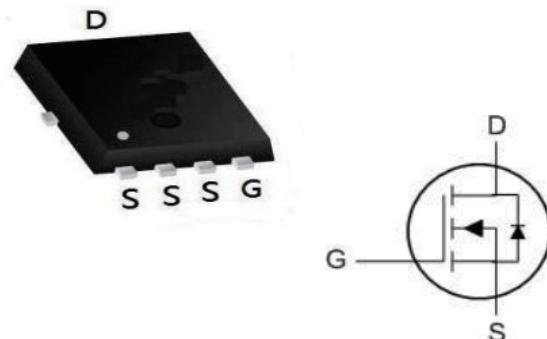


**Product Summary**
**RoHS**

- ★ Green Device Available
- ★ Fast Switching Speed
- ★ 100% EAS Guaranteed
- ★ Advanced Trench MOS Technology

BVDSS	RDS(ON)	ID
40V	6.9mΩ	60A

**Applications**
**PDFN3X3 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current <sup>1</sup>	60	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current <sup>1</sup>	35	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	130	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	48	mJ
$I_{AS}$	Avalanche Current	35	A
$P_d @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	39	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	60	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.2	°C/W

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\text{\mu A}$	40	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=12\text{A}$	---	6.9	8.5	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=10\text{A}$	---	10	15	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=250\text{\mu A}$	1.35	---	3	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=32\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{\mu A}$
		$\text{V}_{\text{DS}}=32\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{R}_g$	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.7	---	$\Omega$
$\text{Q}_g$	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=20\text{V}$ , $\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=12\text{A}$	---	5.8	---	$\text{nC}$
$\text{Q}_{\text{GS}}$	Gate-Source Charge		---	3	---	
$\text{Q}_{\text{GD}}$	Gate-Drain Charge		---	1.2	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=15\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_g=3.3\Omega$ $\text{I}_D=1\text{A}$	---	14.3	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	5.6	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	20	---	
$\text{T}_f$	Fall Time		---	11	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	690	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	193	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	38	---	

## Diode Characteristics

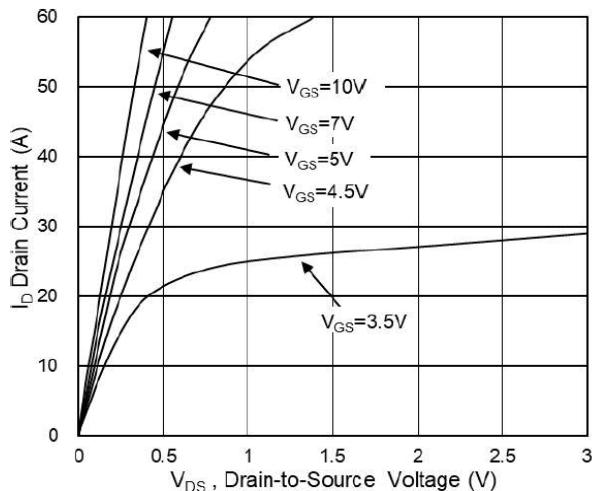
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,5</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	60	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

## Notes:

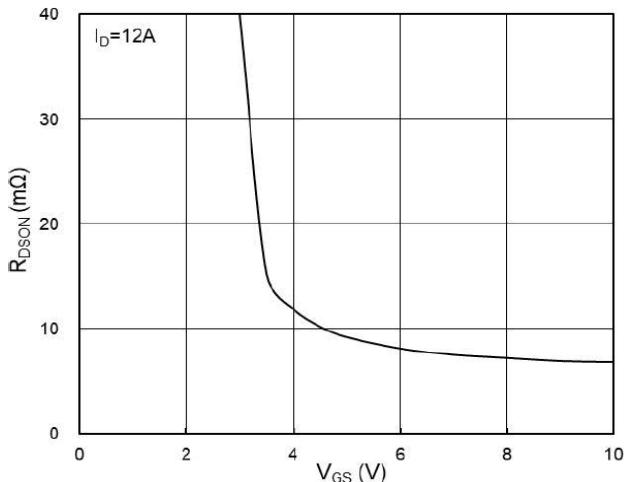
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\text{\mu s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{L}=0.1\text{mH}$ , $\text{IAS}=31\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Electrical and Thermal Characteristics (Curves)

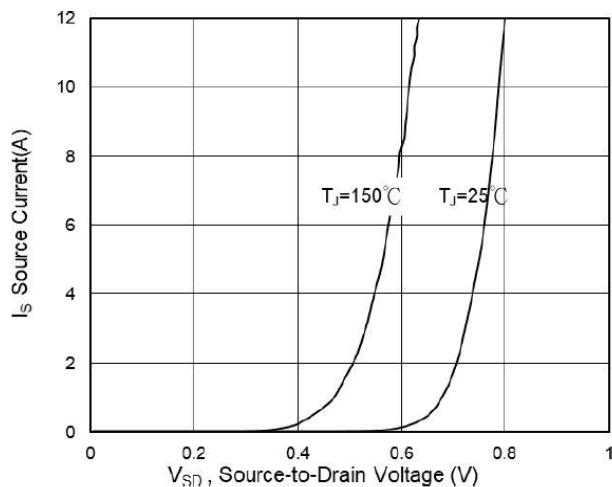
**Figure 1: Output Characteristics**



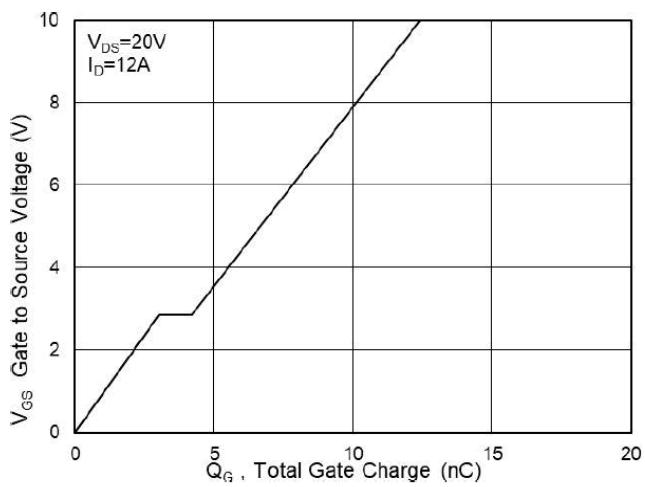
**Figure 2: On-Resistance vs G-S Voltage**



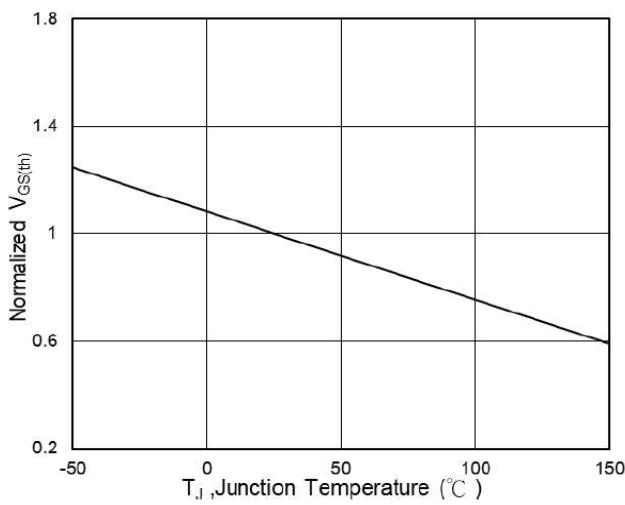
**Figure 3: Source Drain Forward Characteristics**



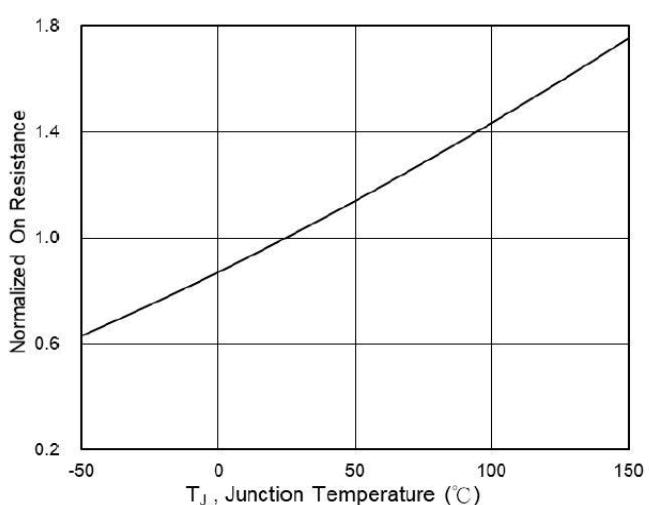
**Figure 4: Gate-Charge Characteristics**



**Figure 5: Normalized V<sub>G  |</sub> vs T<sub>J</sub>**



**Figure 6: Normalized RDSON vs TJ**



## Typical Performance Characteristics

Figure 7: Capacitance

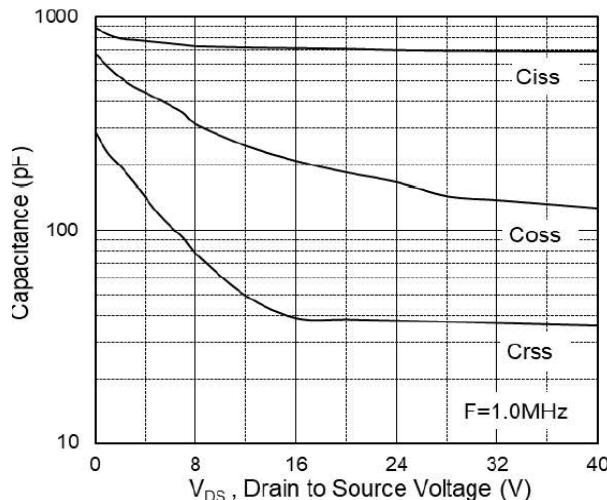


Figure 8: Safe Operating Area

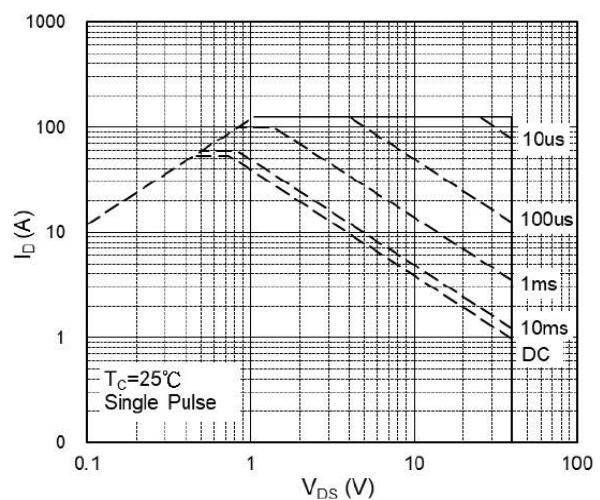


Figure 9: Normalized Maximum Transient Thermal Response

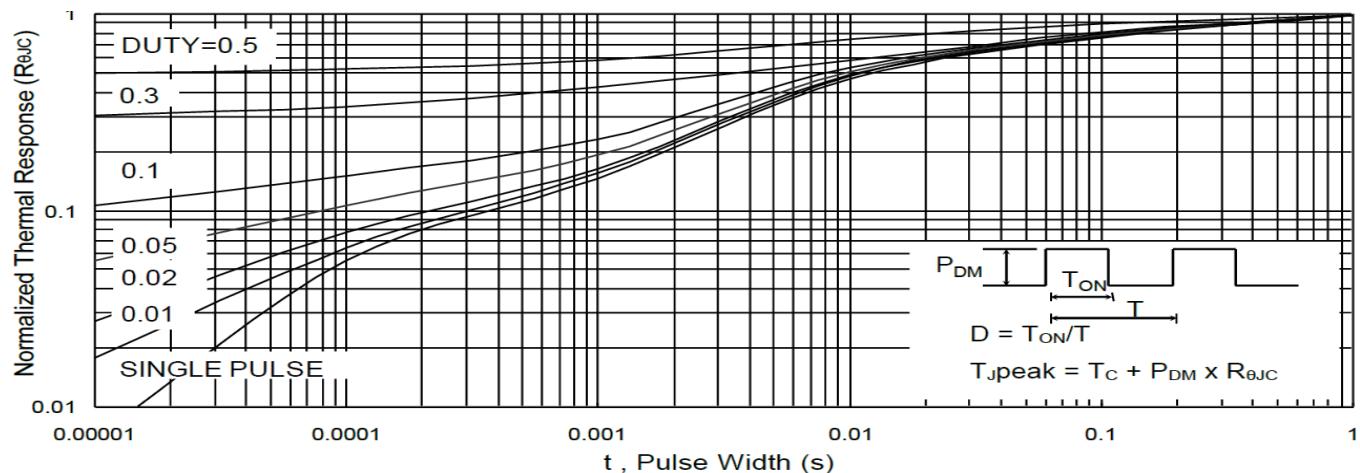


Figure 10: Switching Time Waveform

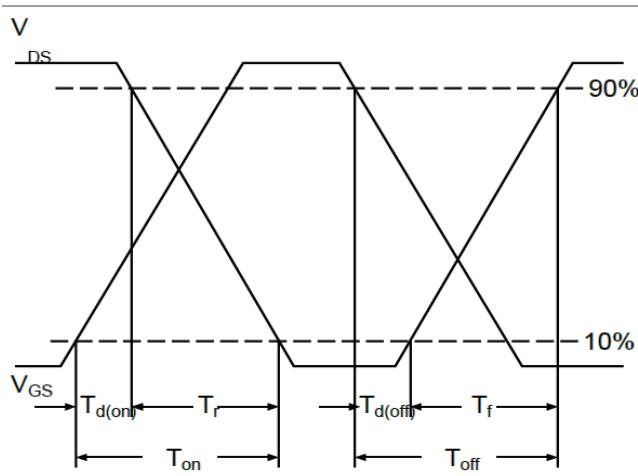
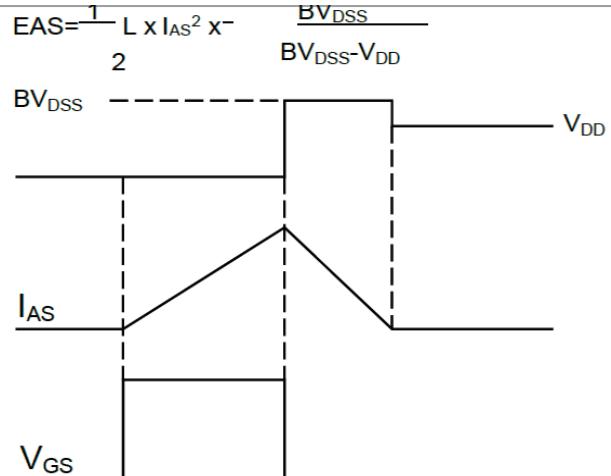
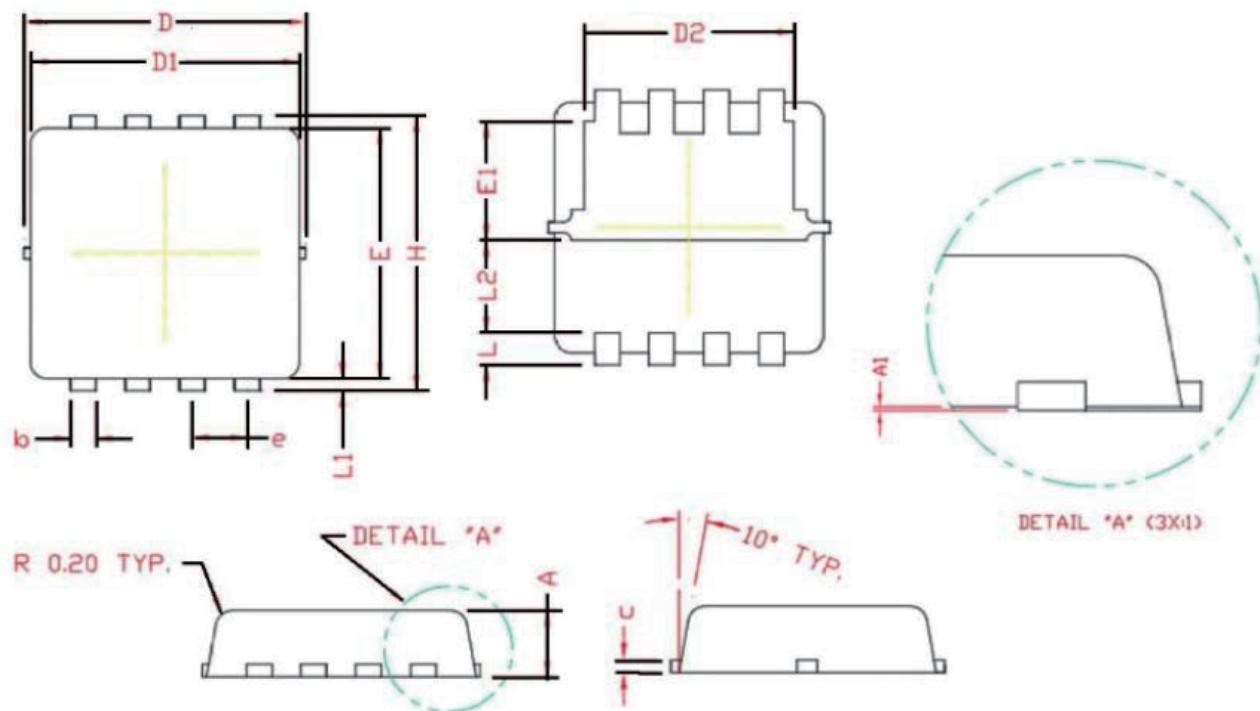


Figure 11: Unclamped Inductive Waveform





## PDFN3\*3-8L Package Information



## COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		